

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.228696**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001460	1000000	6384.02246094		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.122431	975000	535344		
		Iron (Fe)	7439-89-6	0.003014	24000	13179.0703125		
		Phosphorus (P)	7723-14-0	0.000038	300	166.159469604		
		Zinc (Zn)	7440-66-6	0.000088	700	384.790374756		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.125571</b>	<b>1000000</b>	<b>549074</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003749	1000000	16392.6464844		
		<b>External Plating Total:</b>				<b>0.003749</b>	<b>1000000</b>	<b>16392.6464844</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001005	1000000	4394.48095703		
<b>Internal Plating Total:</b>				<b>0.001005</b>	<b>1000000</b>	<b>4394.48095703</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000558	750000	2439.92089844		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000186	250000	813.306945801		
<b>Die Attach Total:</b>				<b>0.000744</b>	<b>1000000</b>	<b>3253.2277832</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009848	103000	43061.5390625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085571	895000	374169.28125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	835.170043945		
		<b>Encapsulation Total:</b>				<b>0.095610</b>	<b>1000000</b>	<b>418066</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000557	1000000	2435.54833984		
					<b>TOTAL MASS (g) :</b>	<b>0.228696</b>		